









PRODUCT DATASHEET



- ► PCB / CHIP LED
- ► 1209 (3224) 2.5t
- ► Green (570nm)

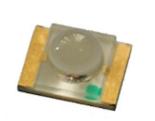
N0G10S56RV











1209 2.5t Series

APPLICATIONS:

- Indication Light
- Switch Light
- 3C Application

FEATURES:

- Package: PCB / CHIP LED Top View Package
- Forward Current: 20mA
- Forward Voltage (typ.): 2.0V
- Luminous Intensity (typ.): 1000mcd@20mA
- Colour: Green
- Wavelength: 570nm
- Viewing angle: 15°
- **Materials:**
 - Die: AlGaInP/GaAs
 - Resin: Epoxy (Water Clear)
- Operating Temperature: -40~+80°C
- Storage Temperature: -40~+85°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - Dominant wavelength
- Soldering methods: Reflow
- Preconditioning: acc. to JEDEC Level 3
- Packing: 8mm tape with 1500/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	PD	75	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

Darameter	Symbol	Values			Unit	Test
Parameter S	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	1.7	2.0	2.5	V	I _F =20mA
Luminous Intensity	I _V	500	1000	2000	mcd	I _F =20mA
Dominant Wavelength	λ_{D}	565	570	576	nm	I _F =20mA
Peak Wavelength	$\lambda_{ extsf{P}}$		572		nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		16		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		15		deg	I _F =20mA

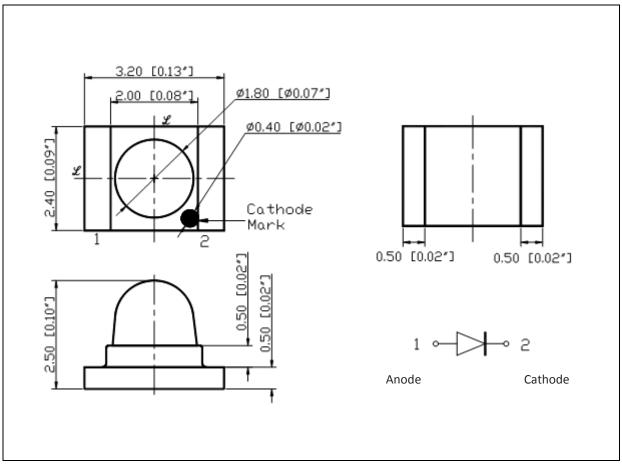
^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%

^{2.} IS standard testing



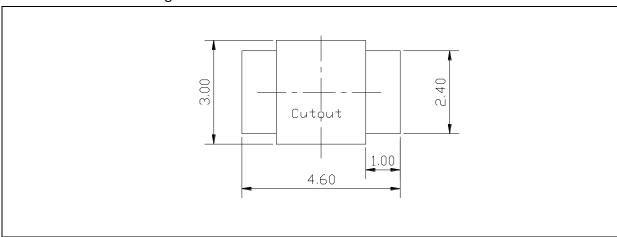
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
D	1.7	2.5	V

Luminous Intensity Classifications (I_F = 20mA):

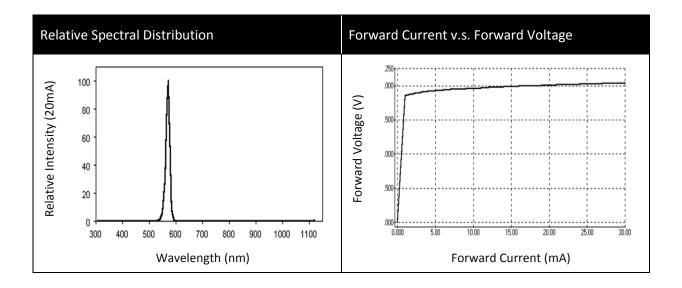
Code	Min.	Max.	Unit
Q	500	630	
R	630	800	
S	800	1000	mad
Т	1000	1250	mcd
U	1250	1600	
V	1600	2000	

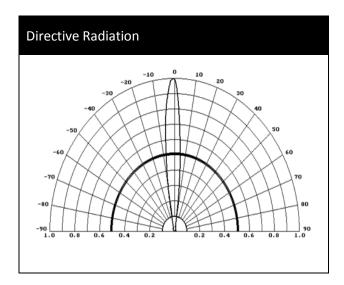
Dominant Wavelength Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
Н	565	568	
I	568	572	nm
J	572	576	



ELECTRO-OPTICAL CHARACTERISTICS:

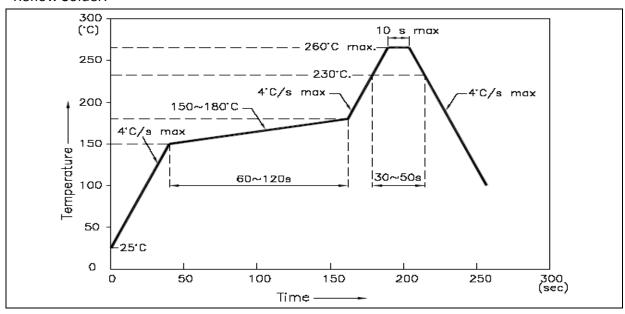






RECOMMENDED SOLDERING PROFILE:

Reflow Solder:



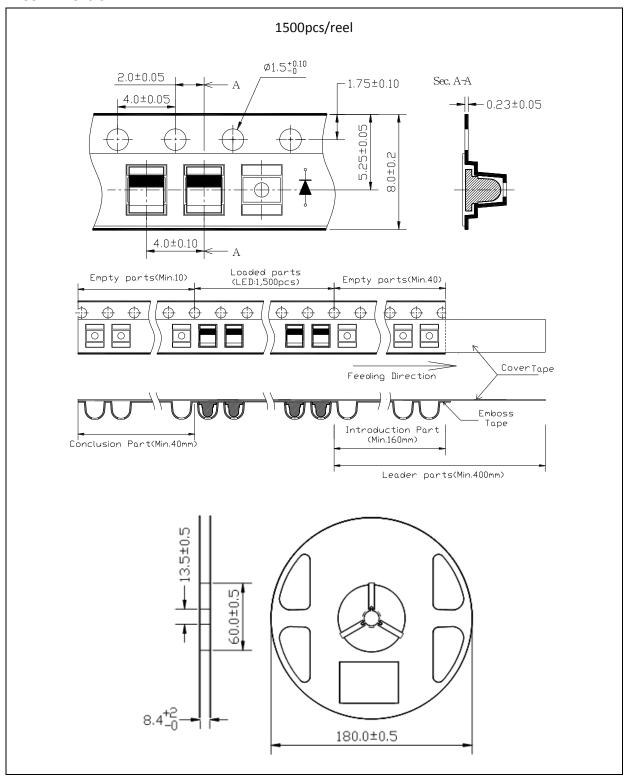
Note:

- 1. Recommend reflow temperature 245°C.
- 2. Maximum reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

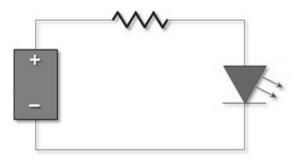
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	11/08/2015	Datasheet set-up.